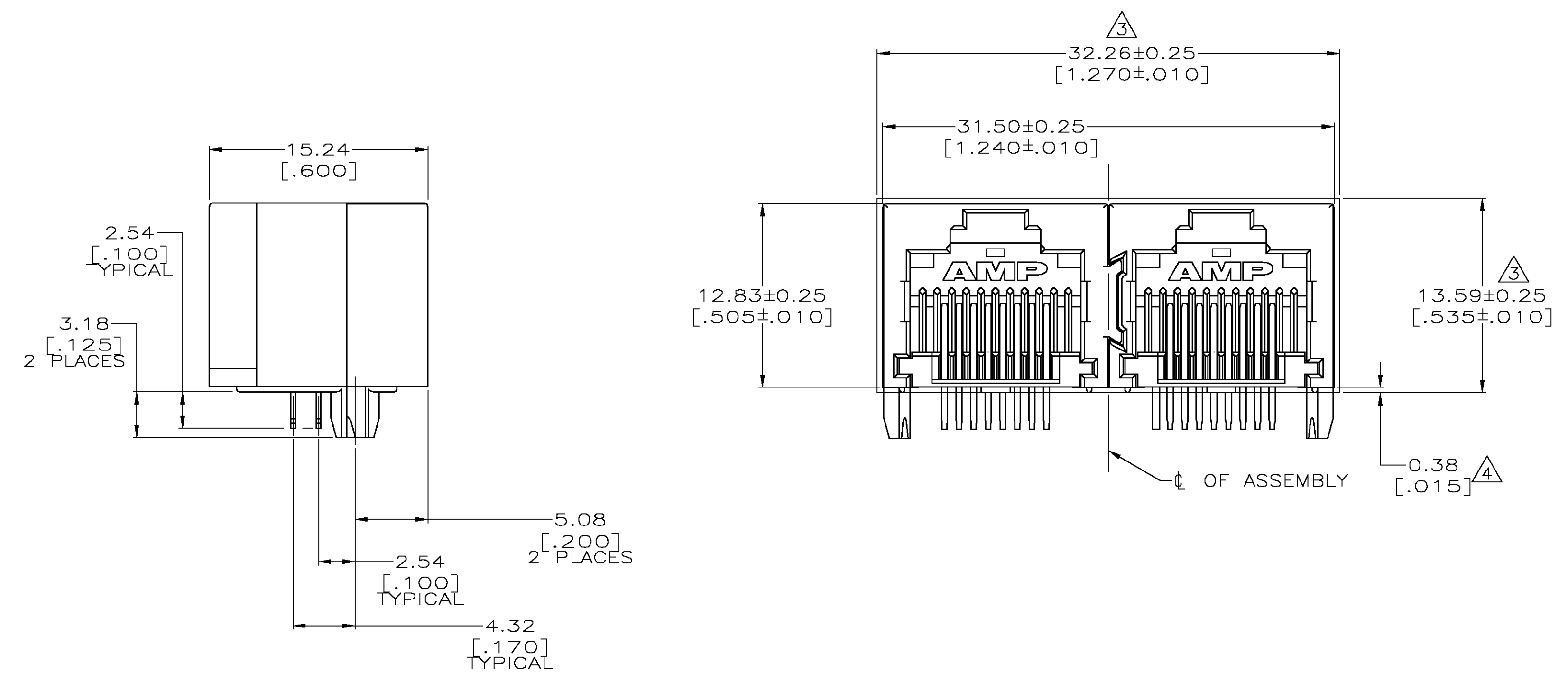
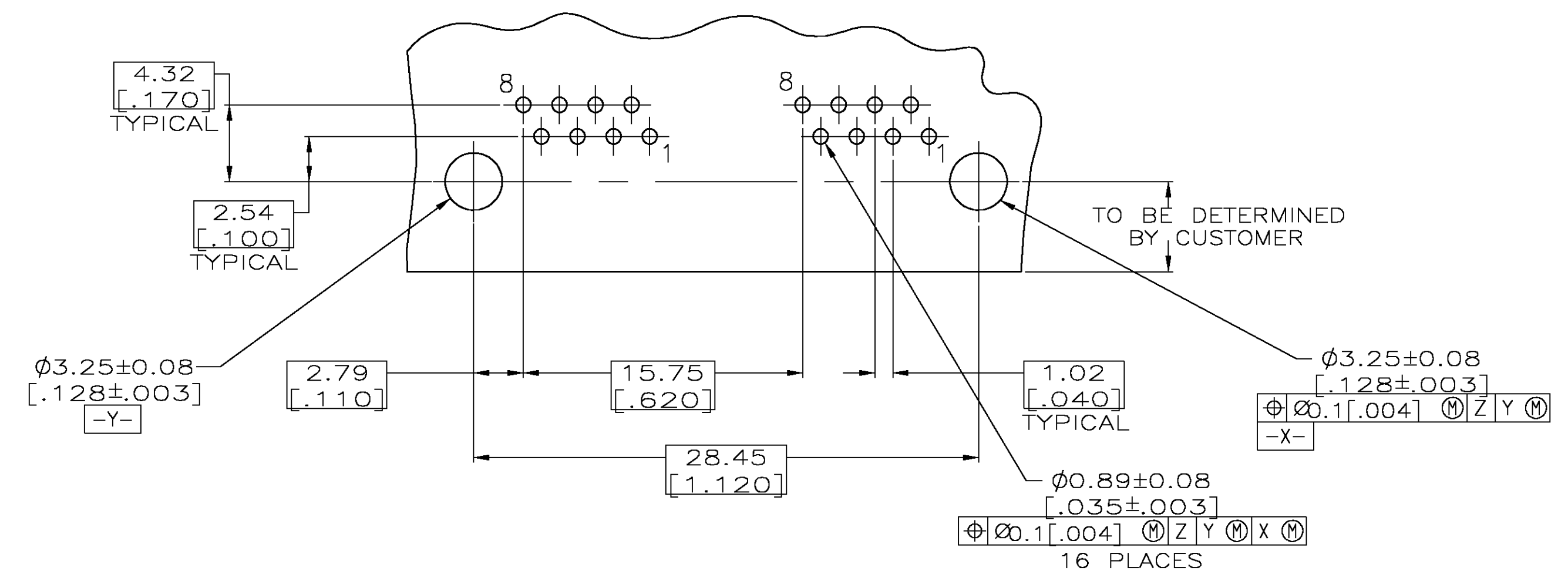
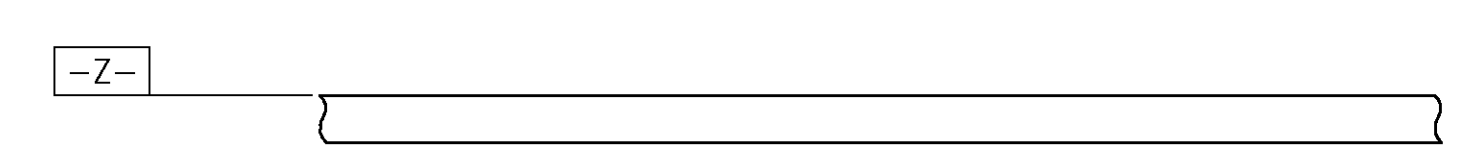


LOC		DIST		REVISONS			
P	LTR	DESCRIPTION	DATE	DNW	APVD		
A		ECOS11-0201-04	08JUNE2005	LAM	SF		



- MATERIAL:  
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; IR REFLOW SOLDERING PROCESS COMPATIBLE.  
 TERMINALS - .36[.014] THICK PHOS BRONZE PLATED WITH 3.81μm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27 μm [ .000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27 μm [ .000050] MINIMUM THICK NICKEL.
  - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.  
 ▲ SUGGESTED CLEARANCE BETWEEN BOTTOM OF CONNECTOR AND BOTTOM PANEL OPENING.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
 (COMPONENT SIDE)

5406526-1  
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DNW T. WOOTEN / L.A. MAYER 08JUNE2005	08JUNE2005	Tyco Electronics Corporation Harrisburg, Pa 17105-3608	
DIMENSIONS: mm		CHK J. WESTMAN 08JUNE2005	08JUNE2005	NAME S. FLICKINGER	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC 108-1163-4		RESTRICTED TO	
0 PLC ± -		APPLICATION SPEC 114-2154		SIZE A1	
1 PLC ± -		WEIGHT -		CAGE CODE 00779	
2 PLC ± -		SCALE 4:1		DRAWING NO 5406526	
3 PLC ± -		SHEET 1 OF 1		REV A	
4 PLC ± -		CUSTOMER DRAWING			